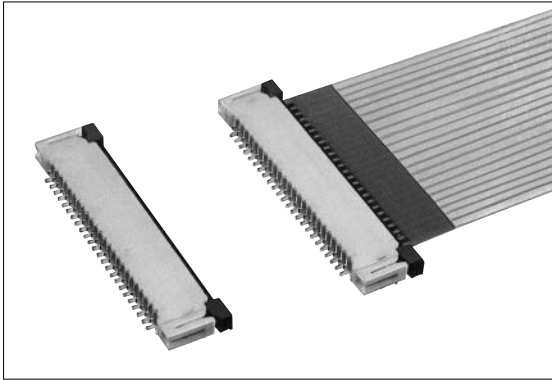


# FP-8 Series 0.8mm Pitch (SMT)



### ■ Features

1. Low profile of 2.0mm height when mounted.
2. Using the ZIF structure.
3. Supplied in the embossed taping with automatic mounter.
4. Lower contact design.

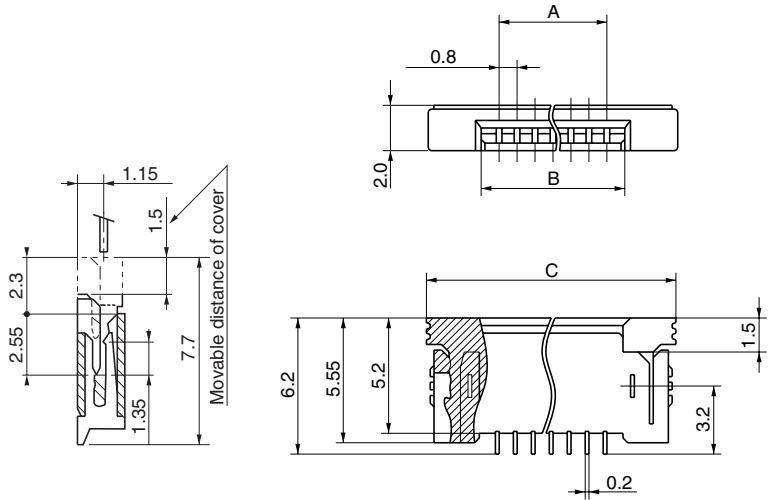
### ■ Specification

1. Rating : 0.5A, 50V AC/DC
2. Contact Resistance : 30mΩ, max., initially
3. Insulation Resistance : 1000MΩ, min. at 500V DC
4. Withstanding Voltage : 500V AC (for one minute)
5. Operating Temperature Range : -25°C to +70°C

### ■ Material and Plating

- Housing : Thermoplastic Resin, Natural Color, 94V-0
- Cover : Thermoplastic Resin, Natural Color, 94V-0
- Contact : Cu Alloy, Au Plating
- Hold-down : Cu Alloy, Sn Plating

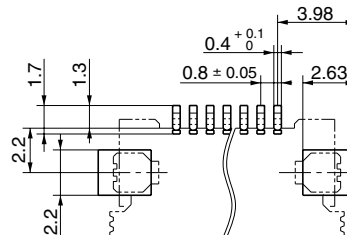
● CFP06 -03 F  
 ↑  
 No. of Pins



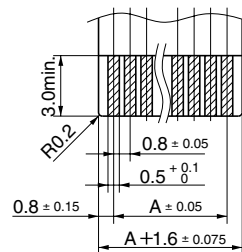
<input type="checkbox"/> <input type="checkbox"/> No. of Pins	A	B	C
18	13.6	15.325	20.425
20	15.2	16.925	22.025
22	16.8	18.525	23.625
24	18.4	20.125	25.225
30	23.2	24.925	30.025

<input checked="" type="checkbox"/> <input checked="" type="checkbox"/>	Packing Style	pcs/reel
01	Embossed Taping	1000
02	Pack in Bulk	—

### ■ P.C. Board Dimension



### ■ Applicable FPC Dimension (t=0.3±0.05)



- FPC plating to recommend : Au plating